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This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (previously presented): A surface acoustic wave device comprising:
first and second longitudinally coupled resonator type surface acoustic wave filters, each of said first and second surface acoustic wave filters having a piezoelectric substrate, at least one interdigital electrode transducer disposed on the piezoelectric substrate, and at least one reflector disposed on the piezoelectric substrate;

a package having the first and second surface acoustic wave filters mounted therein and electrode lands electrically connected to each of the first and second surface acoustic wave filters; and

a plurality of bonding wires electrically connecting each of the first and second surface acoustic wave filters to the electrode lands of the package, wherein the bonding wires are arranged so as not to pass over both of the at least one interdigital electrode transducer and the at least one reflector of either of the first and second surface acoustic wave filters; wherein

said at least one interdigital electrode transducer and said at least one reflector of each of the first and second surface acoustic wave filters is made of a metal having a heavier mass than that of aluminum or an alloy including the metal.

Claim 2 (canceled).

Claim 3 (original): A surface acoustic wave device according to Claim 1, wherein the piezoelectric substrate is a quartz substrate.

Claim 4 (original): A surface acoustic wave device according to Claim 1, wherein

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the at least one interdigital electrode transducer is made of one of tantalum, Au, W, Mo, Ni, Cu, Co, Cr, Zn, Fe, and Mn.

Claim 5 (original): A surface acoustic wave device according to Claim 1, wherein a first plurality of the interdigital electrode transducers are disposed on the piezoelectric substrate along a surface acoustic wave propagation direction, and a first plurality of the reflectors are disposed on both sides, in the surface acoustic wave propagation direction, of an area where the first plurality of the interdigital electrode transducers are disposed, and a second plurality of interdigital electrode transducers are disposed along the surface acoustic wave propagation direction at a location separated in the direction at approximately a right angle to the surface acoustic wave propagation direction, and a second plurality of reflectors disposed on both sides, in the surface acoustic wave propagation direction, of the area where the second plurality of interdigital electrode transducers are provided.

Claim 6 (canceled).

Claim 7 (previously presented): A communication device comprising at least one surface acoustic wave device, the at least one surface acoustic wave device including:

first and second longitudinally coupled resonator type surface acoustic wave filters, each of the first and second surface acoustic wave filters having a piezoelectric substrate, at least one interdigital electrode transducer disposed on the piezoelectric substrate, and at least one reflector disposed on the piezoelectric substrate;

a package having the first and second surface acoustic wave filters mounted therein and electrode lands electrically connected to each of the first and surface acoustic wave filters; and

a plurality of bonding wires electrically connecting each of the first and second surface acoustic wave filters to the electrode lands of the package, wherein the bonding

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wires are arranged so as not to pass over the at least one interdigital electrode transducer and the at least one reflector of the surface acoustic wave element; wherein said at least one interdigital electrode transducer and said at least one reflector of each of the first and second surface acoustic wave filters is made of a metal having a heavier mass than that of aluminum or an alloy including the metal.

Claim 8 (canceled).

Claim 9 (original): A communication device according to Claim 7, wherein the piezoelectric substrate is a quartz substrate.

Claim 10 (original): A communication device according to Claim 7, wherein the at least one interdigital electrode transducer is made of one of tantalum, Au, W, Mo, Ni, Cu, Co, Cr, Zn, Fe, and Mn.

Claim 11 (original): A communication device according to Claim 7, wherein a first plurality of the interdigital electrode transducers are disposed on the piezoelectric substrate along a surface acoustic wave propagation direction, and a first plurality of the reflectors are disposed on both sides, in the surface acoustic wave propagation direction, of an area where the first plurality of the interdigital electrode transducers are disposed, and a second plurality of interdigital electrode transducers are disposed along the surface acoustic wave propagation direction at a location separated in the direction at approximately a right angle to the surface acoustic wave propagation direction, and a second plurality of reflectors disposed on both sides, in the surface acoustic wave propagation direction, of the area where the second plurality of interdigital electrode transducers are provided.

Claims 12-15 (canceled).